

SOT2031-1

FBGA576, fine-pitch ball grid array package, 576 terminals,
0.75 mm pitch, 19 mm x 19 mm x 2.011 mm body

19 July 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA576
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-06-2019
Manufacturer package code	98ASA01378D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	19	-	mm
package width	-	19	-	mm
package height	-	2.011	-	mm
nominal pitch	-	0.75	-	mm
actual quantity of termination	-	576	-	



FBGA576, fine-pitch ball grid array package, 576 terminals, 0.75 mm pitch, 19 mm x 19 mm x 2.011 mm body

2 Package outline

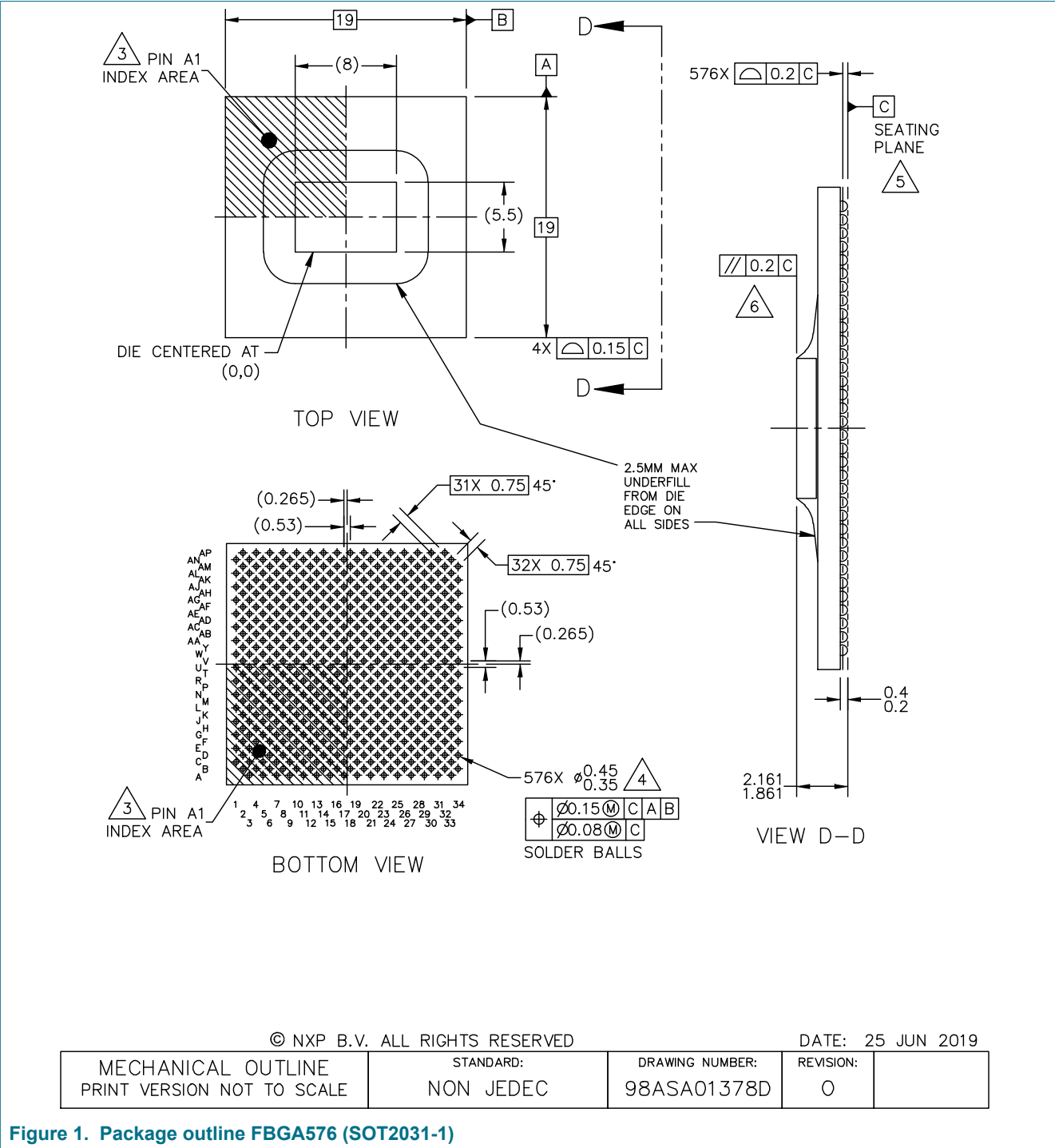
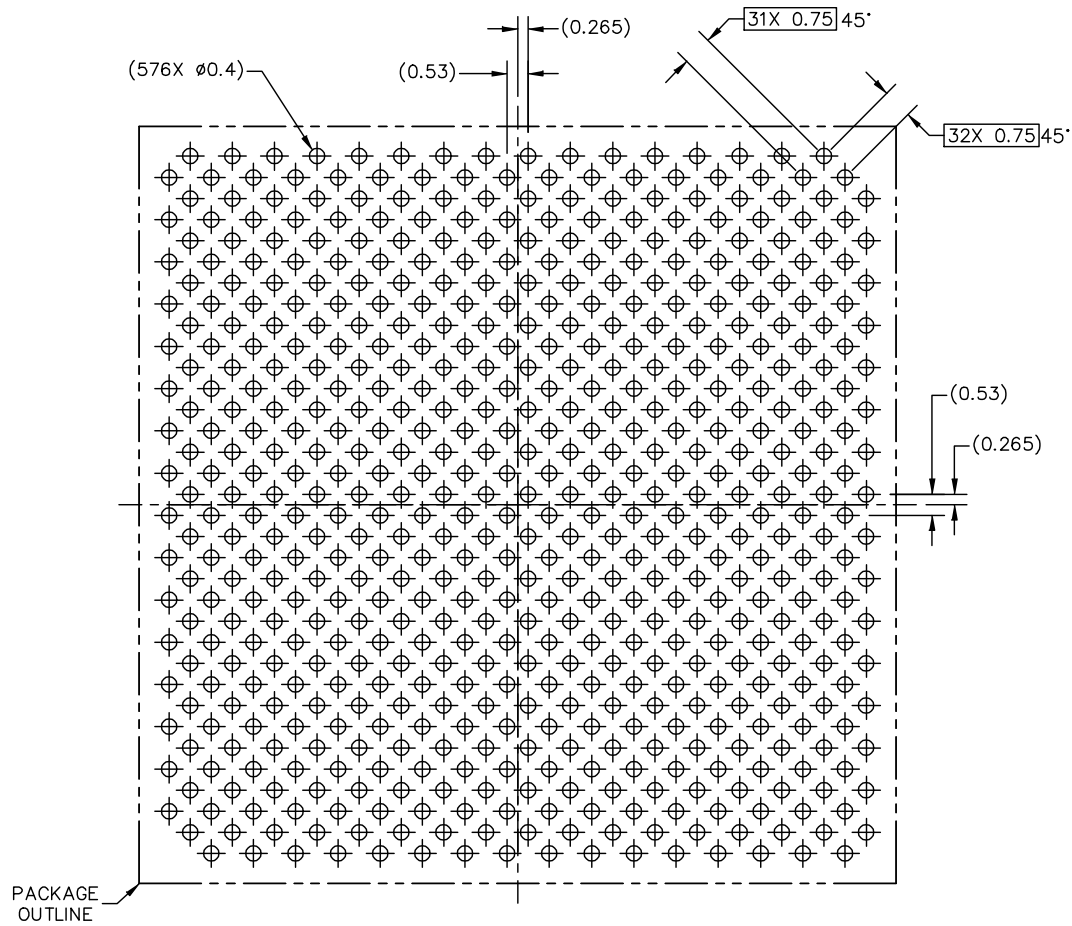


Figure 1. Package outline FBGA576 (SOT2031-1)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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Figure 2. Reflow soldering footprint part1 of FBGA576 (SOT2031-1)

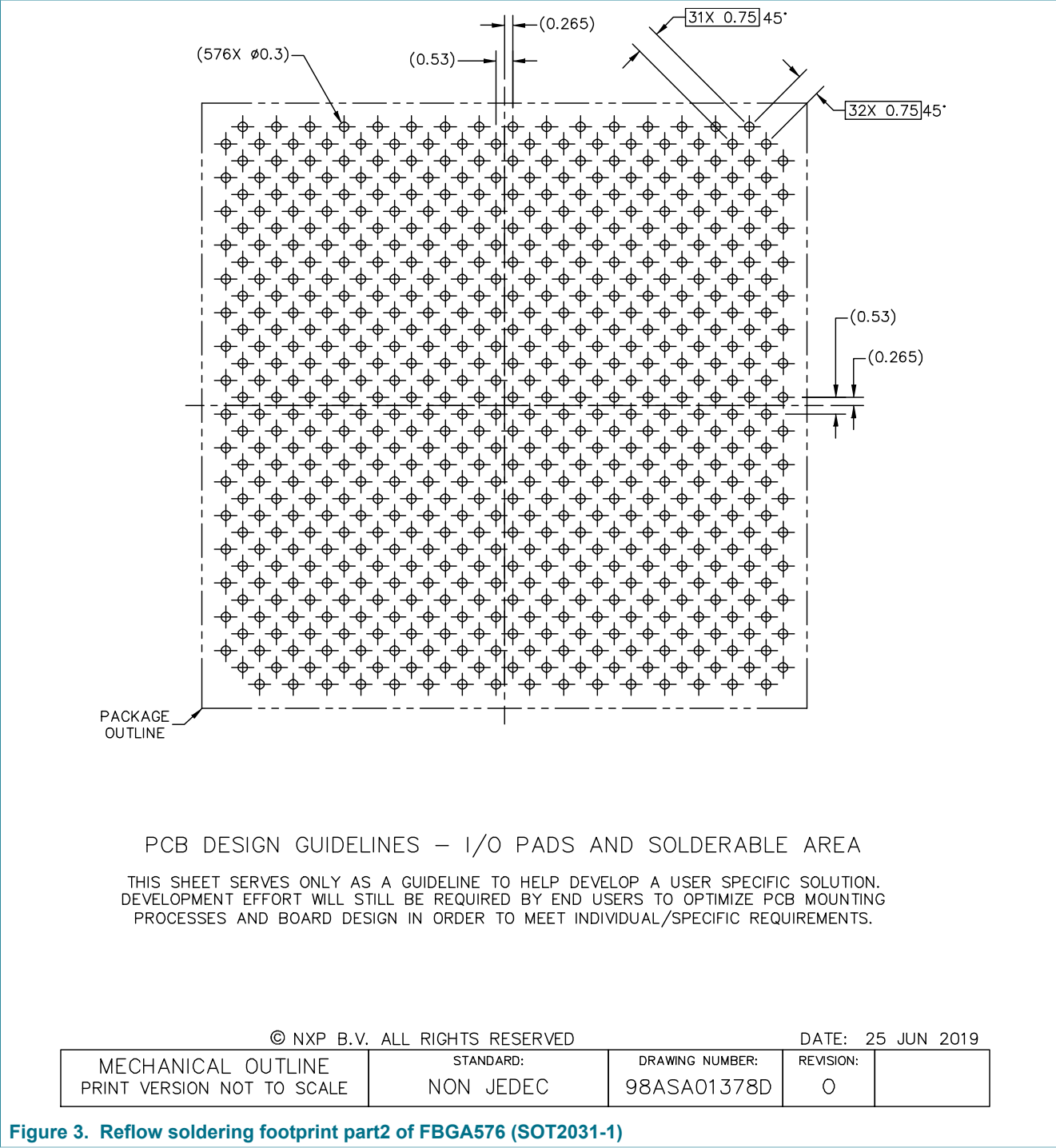
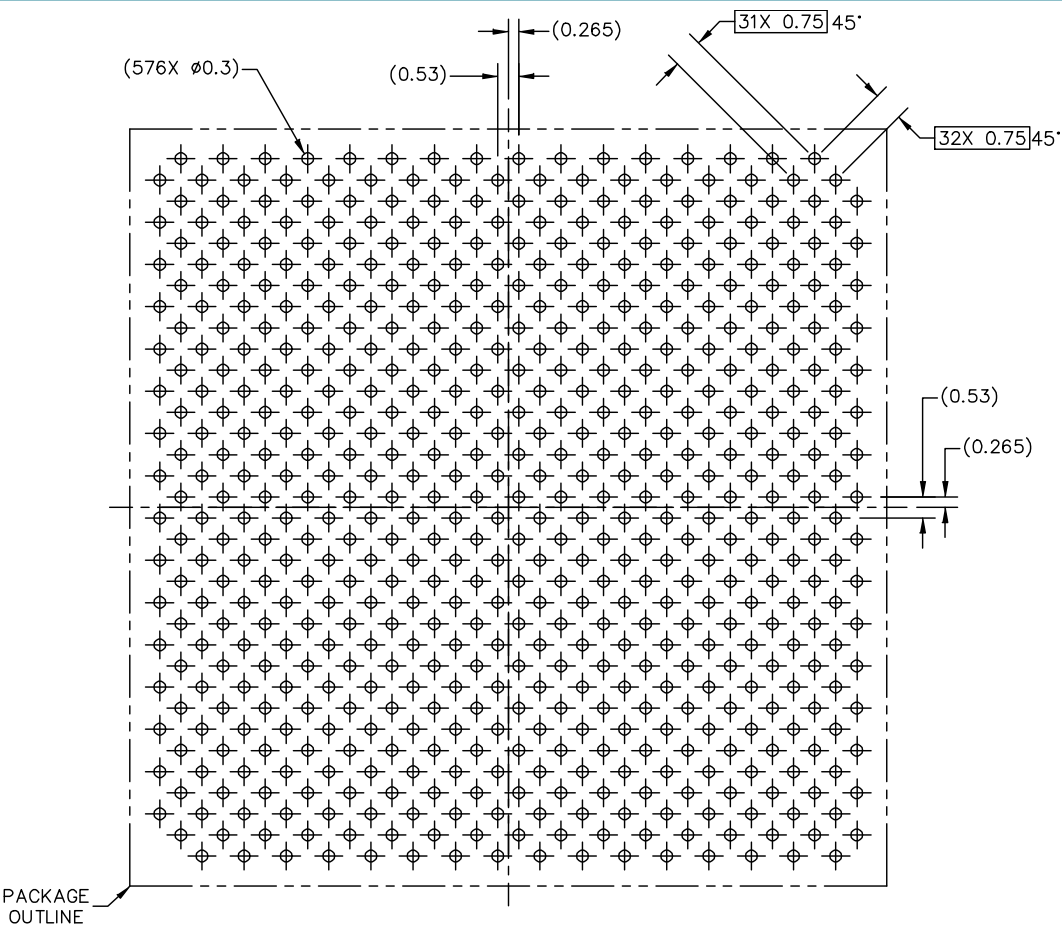


Figure 3. Reflow soldering footprint part2 of FBGA576 (SOT2031-1)



RECOMMENDED STENCIL THICKNESS 0.1MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 of FBGA576 (SOT2031-1)

FBGA576, fine-pitch ball grid array package, 576 terminals, 0.75 mm pitch, 19 mm x 19 mm x 2.011 mm body

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note FBGA576 (SOT2031-1)

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Contents

1	Package summary	1
2	Package outline	2
3	Soldering	3
4	Legal information	7